

# Stellar SR6 G6 line—32-bit Arm® Cortex®-R52+ automotive integration MCU

## 4× Cortex®-R52+ cores, 16 MB NVM (2× 15 MB “OTA X2”) 3.8 MB RAM, with embedded virtualization, safety, and security




FPBGA476  
(21.3 × 21.3 mm)



FPBGA292  
(17 × 17 mm)



### Features

- AEC-Q100 
- SR6 integration MCUs:
  - Have superior real-time and safe performance (with highest ASIL-D capability)
  - Bring hardware-based virtualization technology to MCUs for simplified multiple software integrations at optimized performance
  - Have built-in fast and cost-effective OTA reprogramming capability (with built-in dual-image storage)
  - Offer high-speed security cryptographic services, for example for network authentication

### Cores and accelerators

- 4 × 32-bit Cortex®-R52+ cores (2 of them with checker cores, and 2 in split-lock configuration):
  - Configurable as either 4 cores (2 of them in lockstep configuration) or 3 cores (all of them in lockstep configuration)
  - Arm® v8-R compliant
  - Single precision floating-point unit (FPU)
  - New privilege level for real-time virtualization
  - 1 core with Neon™ extensions (for example SIMD, dual precision FPU)
- 2 Cortex®-M4 multipurpose accelerators, both in lockstep configuration
- 4 eDMA engines in lockstep configuration
- Ethernet switch:
  - 2 external gigabit (GB) ports with line-rate MACsec
  - 6 data + 1 host internal virtualized ports
  - Time-sensitive networking
  - Audio-video transport protocol (AVTP)
  - Media clock recovery/generation
  - L2 forwarding, L2+ routing
  - ASIL-B target

### Memories

- Up to 16 MB on-chip nonvolatile memory (NVM):
  - PCM (phase-change memory) as nonvolatile memory
  - 15 MB code NVM, with embedded memory replication for OTA (over-the-air) reprogramming with up to 2× 15 MB
  - 1024 KB HSM-dedicated code NVM
- 384 KB data NVM (256 KB + 128 KB dedicated to HSM)
- Up to 3840 KB on-chip general-purpose SRAM

Product summary	
Part number	Package
SR6G6C6	FPBGA476
SR6G6C4	FPBGA292

**Security: 2<sup>nd</sup> generation hardware security module**

- Cybersecurity: ISO/SAE 21434 compliance (refer to the cybersecurity reference manual for details)
- On-chip high-performance security module with full support for e-safety vehicle intrusion protected applications (EVITA)
- Symmetric and asymmetric cryptography processor
- High-performance lock-stepped AES-light security subsystem for fast ASIL-D cryptographic services
- Two MACsec accelerators integrated on each Ethernet link

**Safety: comprehensive new-generation ASIL-D safety concept**

- New state-of-the-art safety measures at all levels of the architecture for most efficient implementation of ISO 26262 ASIL-D functionalities
- Complete hardware virtualization architecture built on Cortex<sup>®</sup>-R52+ new privilege mode (best-in-class software isolation, real-time support for multiple virtual machines/applications)

**Device standby/low-power modes**

- Versatile low-power modes
- Ultra-low power: standby mode for lowest quiescent current with optimized active subsystem (for example standby RAM) and wake-up capability
- Smart low-power: smart power mode with Cortex<sup>®</sup>-M4 subsystem, extended communications interfaces, and ADC peripheral

**Peripheral, I/O, and communication interfaces**

- 24 LINFlexD modules
- 1 dual-channel FlexRay controller
- 10 queued serial peripheral interface (SPIQ) modules
- 2 DSPI with shifted PWM serialization support for lighting applications
- 6 I<sup>2</sup>C interfaces
- Enhanced audio support that enables audio over Ethernet:
  - Ethernet controller with AVB support
  - Medial clock recovery with integrated audio PLL
  - Two integrated interchip sound (I<sup>2</sup>S)/time-division multiplexed (TDM) interfaces
  - Integrated sample rate converters (6 channels on each I<sup>2</sup>S interface)
- 2 SENT modules (4 channels each)
- 2 PSI5 modules (2 channels each)
- 1 peripheral component interconnect express (PCIe) Gen2 controller
  - Gen2 PHY: Gen1 (2.5 GT/s), Gen2 (5.0 GT/s)
  - Gen3 MAC
  - Two lanes
  - Configurable controller with one or two lanes
- Enhanced analog-to-digital converter system with:
  - 4 separate 12-bit SAR analog converters (including one supervisor/safety ADC).
  - One 9-bit SAR analog converter for device standby/low-power mode
- Advanced timed I/O capability:
  - Generic timer module (GTM4184)

- Communication interfaces:
  - Two 10/100/1000 Mbit/s Ethernet controllers compliant with IEEE 802.3-2008: IPv4 and IPv6 checksum modules, AVB, VLAN, and EMC optimized SGMII
  - Two 10 Mbit/s Ethernet controllers compliant with 10BASE-T1S and the OPEN Alliance 3-pin (OA3p) interface
  - 15 modular controller area network (MCAN) modules, and 1 time-triggered controller area network (M\_TTCAN), all supporting flexible data rate (ISO CAN FD<sup>®</sup>)
  - 2 CAN XL<sup>®</sup> interfaces

**External memory interfaces**

- 2 octo-SPI IPs to support HyperBus<sup>™</sup> memory (flash/RAM) devices
- 1 SDMMC interface

# 1 Introduction

## 1.1 Document overview

This document provides a summary of the target specification and features of the SR6G6C6 and SR6G6C4 devices. For detailed information, refer to the device Datasheet and device Reference manual.

*Note:* For information on the Cortex®-R52+ and Cortex®-M4 cores, refer to the technical reference manuals, available from the [www.arm.com](http://www.arm.com) website.

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## 1.2 Description

Stellar integration MCUs have been designed to meet the requirements of domain controllers and ECUs with high integration requested in the architectures of connected updatable automated and electrified cars. They have superior real-time and safe performance (with highest ASIL-D capability). Bringing hardware-based virtualization technology to MCUs, they ease the development and integration of multiple source software onto the same hardware while maximizing the resulting software performance. They offer high-efficiency OTA reprogramming capability with fast new image download and activation at almost no memory overhead thanks to SR6 unique built-in dual-image storage tailored to OTA reprogramming needs. They also provide high-speed security cryptographic services, for instance for network authentication.

**Table 1. SR6G6C6 and SR6G6C4 overview**

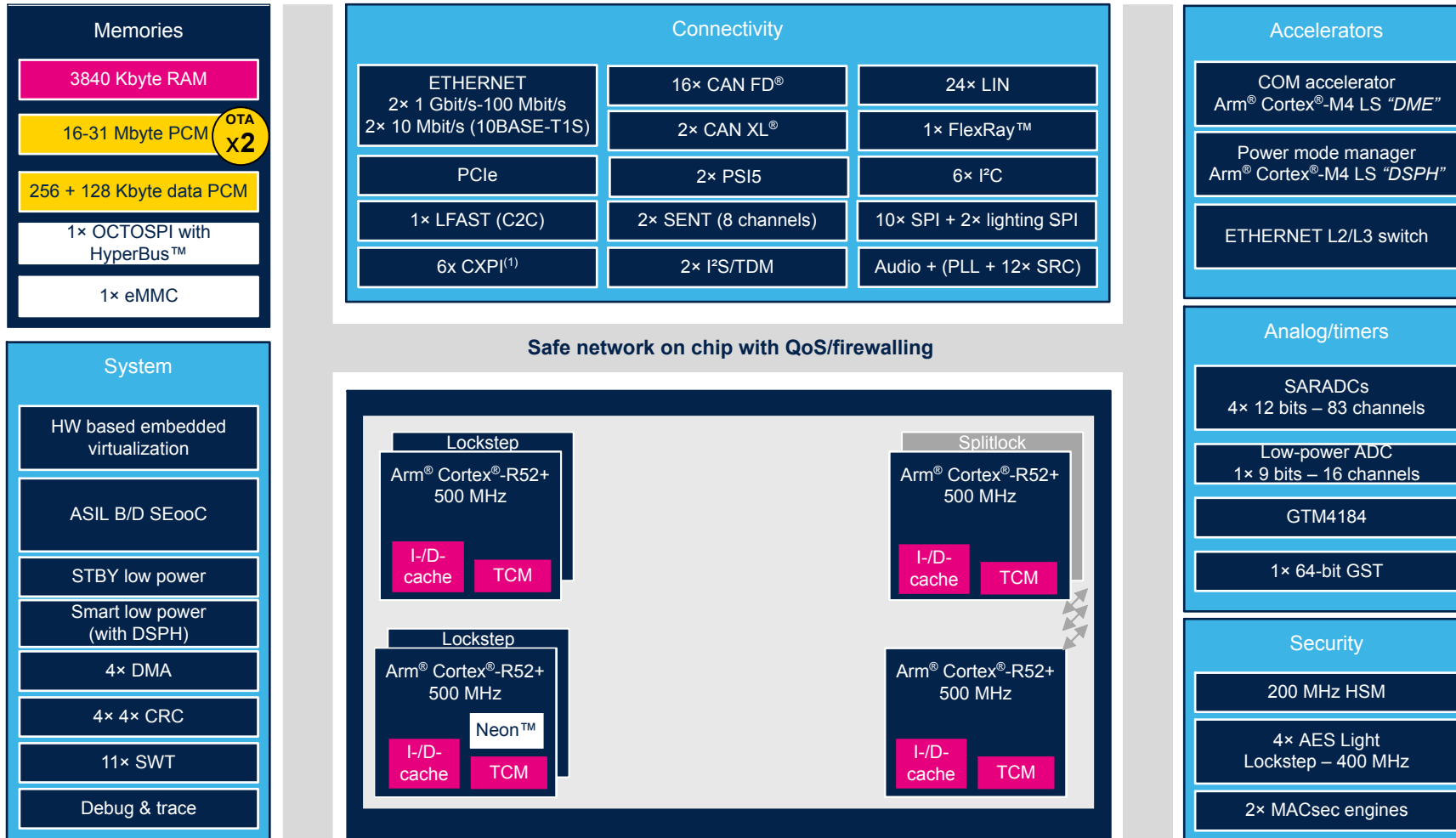
Feature		SR6G6C6 and SR6G6C4
Cortex®-R52+ cores (+ checker cores)		4 cores (+2 checkers), configurable as 3 cores (+3 checkers)
Neon™ (with SIMD, dual precision floating point)		1
Cache (instruction/data) per core in Kbyte		32/32
Core memory protection unit (regions), several additional protection mechanisms in the architecture, for example: NOC firewalls	Hypervisor (EL2)	24
	OS (EL1)	24
Code NVM	Overall including HSM in Mbytes	16
	Cluster code NVM in Mbytes	15
	HSM code NVM in Kbytes	1024
Code NVM built-in memory replication for OTA reprogramming (not supported by HSM) in Mbytes		Up to 2× 15
Data NVM in Kbytes		384
RAM in Kbytes		3840
Hardware security module (HSM) - 2 <sup>nd</sup> generation		Yes
AES-Light (cryptographic services)		4
Arm® Cortex®-M4	Multipurpose accelerator in lockstep (DSPH)	1
	Multi-purpose accelerator in lockstep (DME)	1
Standby and smart power modes		Yes
eDMA engines (number of channels, more channels through muxes/channel)	Engine	4
	Channel	3× 32 1× 64

Feature		SR6G6C6 and SR6G6C4
Audio over Ethernet enhancements: <ul style="list-style-type: none"> <li>Ethernet controller with AVB support</li> <li>Media clock recovery (optional: integrated audio PLL)</li> <li>Integrated interchip sound (I<sup>2</sup>S)/time-division multiplexed (TDM) interfaces</li> <li>Optional: integrated sample rate converters</li> </ul>		Yes with integrated audio PLL 2× SRC (6 channels each)
I <sup>2</sup> S with TDM		2
LIN and UART (LINFlexD)		24
CAN_FD		16
CAN_XL		2
SPIQ (with LVDS channel)		10 (0)
SENT	Unit	2
	Channel/unit	15
I <sup>2</sup> C		6
DSPI		2
PSI5	Unit	2
	Channel/unit	2 channels
FlexRay™ (dual channel)		1
Gigabit ethernet IEEE 802.3-2008 compliant	Total	2
	With MII, RMII, RGMII, and SGMII	1
	With RMII and SGMII	1
10BASE-T1S Ethernet MAC and PHY with OA3p, the OPEN Alliance 3-pin interface (for 10BASE-T1S transceivers)		2
Line-rate media access control security (MACsec) accelerators		2
Flexible and safe Ethernet switch (FLEX_SGS) with L2/L2+ routing features: <ul style="list-style-type: none"> <li>IEEE 802.3</li> <li>IEEE 802.1Qav-2009 (forwarding and queuing)</li> <li>IEEE 802.1AS-2011 (time synchronization)</li> <li>IEEE 802.1Qbv-2015 (time-aware shaper)</li> <li>IEEE 1588 PTP (with pulse-per-second output)</li> <li>IEEE 1722 AVBTP (with media clock generation and recovery)</li> </ul>		Yes
PCI Express® (PCIe®) Gen2		2 lanes
SIPI/LFAST interprocessor bus		1
Generic timer modules (GTM4)		GTM4184
High-resolution timer		No
12-bit SAR analog converters		4
9-bit SAR analog converters for low-power modes		1
Octo-SPI (support HyperBus™ memory devices)		Yes
SDMMC interface		Yes
Debug port	Main debug port (JTAG+SWD)	Yes
	Secondary debug port (SWD)	Yes
High-speed off-chip trace lane (multi GBit/s, Aurora™ protocol)		2
Max temperature (target)	Junction temperature	150 °C
Packages	FPBGA476	X
	FPBGA292	X

### 1.3 Block diagram

The figure below shows the top-level block diagram.

Figure 1. Block diagram



1. Emulated by GTM.



## Revision history

**Table 2. Document revision history**

Date	Revision	Changes
18-Oct-2024	1	Initial release.

## Glossary

**ADC** Analog-to-digital converter

**AEC** Automotive Electronics Council. Also known as CDF-AEC for Chrysler-Delco-Ford Automotive Electronics Council. Shortened to AEC.

**AES** Advanced encryption standard. Cryptographic algorithm.

**ASIL** Automotive safety integrity level

It is a risk classification system defined by the ISO 26262 standard for the functional safety of road vehicles. There are four ASILs identified by ISO 26262—A, B, C, and D. ASIL A represents the lowest degree and ASIL D represents the highest degree of automotive hazard.

**AVB** Audio-video bridging

**AVTP** Audio-video transport protocol

**BCS** Boot code sector

**BSC** Basic (dimension)

**CAN** Controller area network

**CAN FD**<sup>®</sup> Controller area network flexible data rate

**CAN XL**<sup>®</sup> Controller area network extra long

**CBC** Cipher block chaining

**CDM** Charged device model

**CFB** Cipher feedback

**CGM** Clock generation module

**CMAC** Cipher-based message authentication code

**CMD** Command

**CMOS** Complementary metal-oxide-semiconductor

**COL** Collision detect

Asynchronous receiver signal of the media-independent interface (MII).

**CPHA** Clock phase bit. Selects the clock phase.

**CPOL** Clock polarity bit. Selects the clock polarity.

**CPU** Central processing unit

**CRC** Cyclic redundancy check

**CRS** Carrier sense

Asynchronous receiver signal of the media-independent interface (MII).

**CTI** Arm<sup>®</sup> CoreSight<sup>™</sup> cross-trigger interface

**CTM** Cross-trigger matrix

**CTR** Counter mode

**CXPI** Clock extension peripheral interface

**DAC** Digital-to-analog converter

**DC** Direct current

**DCF** Device configuration format

**DDR** Double data rate

**DMA** Direct memory access

**DME** Data movement engine

**DNL** Differential nonlinearity

**DS** Default speed

**DSPI** Deserial serial peripheral interface

**DTR** Double transfer rate

**eDMA** Enhanced direct memory access

**EMC** Electromagnetic compatibility

**EVITA** e-safety vehicle intrusion protected applications

**FCCU** Fault collection and control unit

**FLEX\_SGS** Flexible safe gateway/switch



<b>FPBGA</b> Fine-pitch-ball-grid-array	<b>MCAN</b> Modular controller area network
<b>FPU</b> Floating-point unit	<b>MCU</b> Microcontroller unit
<b>GB</b> Gigabyte	<b>MEMU</b> Memory error management unit
<b>GPIO</b> General-purpose input/output	<b>MII</b> Media-independent interface
<b>GTM</b> Generic timer module	<b>MSC</b> Microsecond channel
<b>HSM</b> Hardware security module	<b>NoC</b> Network on chip
<b>HSSTP</b> High-speed serial trace probe	<b>NVM</b> Nonvolatile memory
<b>I/O</b> Input/output	<b>OA3p</b> OPEN Alliance 3-pin (interface)
<b>IEC</b> International Electrotechnical Commission	<b>OS</b> Operating system
<b>IEEE</b> Institute of Electrical and Electronics Engineers	<b>OTA</b> Over the air
<b>IPv4</b> Internet protocol version 4	<b>PCIe®</b> Peripheral component interconnect express
<b>IPv6</b> Internet protocol version 6	<b>PHY</b> Physical layer
<b>ISO</b> International Organization for Standardization	<b>PLL</b> Phase-locked loop
<b>I<sup>2</sup>C</b> Inter-integrated circuit	<b>PSI5</b> Peripheral sensor interface (PSI5). An interface for automotive sensor applications.
<b>I<sup>2</sup>S</b> Integrated interchip sound	<b>PTP</b> Precision time protocol
<b>JEDEC</b> Joint Electron Device Engineering Council	<b>PWM</b> Pulse-width modulation
<b>JTAG</b> Joint Test Action Group	<b>RAM</b> Random access memory
<b>KB</b> Kilobyte	<b>RGMII</b> Reduced gigabit media-independent interface
<b>LFAST</b> LVDS fast asynchronous serial transmit interface	<b>RMII</b> Reduced media-independent interface
<b>LIN</b> Local interconnect network	<b>SAR</b> Successive approximation register
<b>LVDS</b> Low-voltage differential signaling	<b>SDMMC</b> Secure digital and MultiMediaCard
<b>M_TTCAN</b> Time-triggered controller area network	<b>SENT</b> Single-edge nibble transmission for automotive applications
<b>MAC</b> Media access control	<b>SeooC</b> Safety element out of context
<b>MACsec</b> Media access control security	<b>SGMII</b> Serial gigabit media-independent interface
<b>MB</b> Megabyte	<b>SIMD</b> Single-instruction multiple data

**SIPI** Serial interprocessor interface

**SPI** Serial peripheral interface

**SPIQ** Queued serial peripheral interface

**SRAM** Static random-access memory

**SRC** Sample rate converter

**ST** STMicroelectronics

**STLA** Signal tap logic analyzer

**SWD** Secondary debug port

**TDM** Time-division multiplexed or multiplexing

**UART** Universal asynchronous receiver/transmitter

**VLAN** Virtual local area network

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